![ATMEL WIRELESS & µC logo]

U2796B

2-GHz Single-Balanced Mixer

Description

The U2796B-FP is a 2-GHz down-conversion mixer for telecommunication systems, e.g. cellular radio, CT1, CT2, DECT, PCN, using Atmel Wireless & Microcontrollers' advanced bipolar UHF technology. The U2796B is well suited for the receiver portion of the RF circuit. Single-balanced structure has been chosen for best noise performance and low current consumption. The IIP3 is programmable.

Electrostatic sensitive device.
Observe precautions for handling.

Features

- Supply-voltage range: 2.7 V to 5.5 V

- Excellent isolation characteristics

- Low current consumption: 3.2 mA without R_{IP3}

- IIP3 programmable

- Input frequency operating range up to 2 GHz

- RF characteristic nearly independent of supply voltage

Benefits

- Stand-alone product

- Low current consumption extends talk time

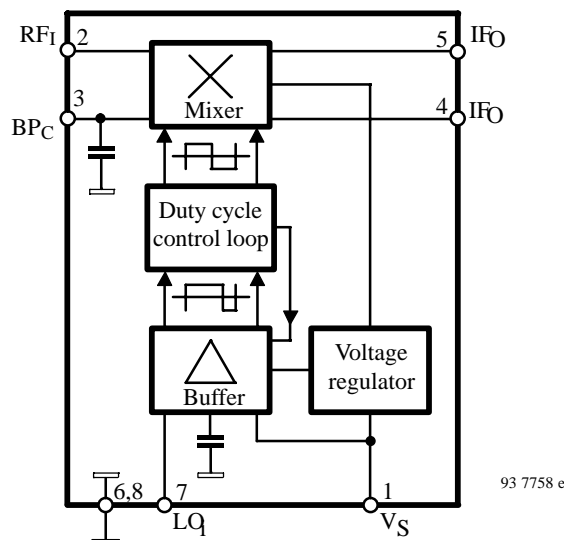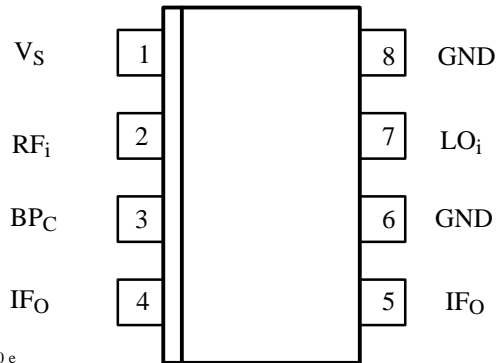- 3-V operation requires only small space for batteries

Block Diagram

Figure 1. Block diagram

Ordering Information

Extended Type Number	Package	Remarks
U2796B-MFP	SO8	Tube
U2796B-MFPG3	SO8	Taped and reeled

U2796B

Pin Description

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Figure 2. Pinning

Pin	Symbol	Function
1	V_S	Supply voltage
2	RF	RF input and IIP3 programming port
3	BP_C	Bypass capacitor
4	IFo	IF output
5	IFo	IF output
6	GND	Ground
7	LO_i	Local oscillator input
8	GND	Ground

Absolute Maximum Ratings

Parameters		Symbol	Value	Unit
Supply voltage	Pin 1	V_S	6	V
Input voltage	Pins 2, 3, 4, 5 and 7	V_i	0 to V_S	V
Junction temperature		T_j	125	°C
Storage temperature		T_{stg}	–40 to +125	°C

Operating Range

Parameters		Symbol	Value	Unit
Supply-voltage range	Pin 1	V_S	2.7 to 5.5	V
Ambient temperature		T_{amb}	–40 to +85	°C

Thermal Resistance

Parameters		Symbol	Value	Unit
Junction ambient	SO8	R_{thJA}	175	K/W

Electrical Characteristics

Test conditions (unless otherwise specified):
V_S = 3 V, f_{LO} = 900 MHz; I_M = 1.2 mA, T_{amb} = 25°C. System impedance Z_O = 50 Ω

Parameters	Test conditions / Pin	Symbol	Min.	Typ.	Max.	Unit
Supply voltage	Pin 1	V_S	2.7		5.5	V
Supply current	R_{IP3} = ∞, Pin 1	I_S	2.8	3.2	3.7	mA
Conversion power gain	RL = 3 kΩ, R_{IP3} = ∞ f_{LO} = 900 MHz	PG_C		9		dB
Figure 4	f_{LO} = 1700 MHz f_{IF} = 45 MHz			9		

Electrical Characteristics (continued)

Parameters	Test conditions / Pin	Symbol	Min.	Typ.	Max.	Unit
Isolation						
LO spurious at RF_{in}	$Pi_{LO} = -10$ dBm Figure 5 Pin 7 to 2	IS_{LORF}			-35	dBm
RF to LO	$Pi_{RF} = -25$ dBm Pin 2 to 7 $f_{LO} = 900$ MHz	IS_{RFLO}	30	40		dB
Figure 6	$f_{LO} = 1700$ MHz			20		
Operating frequencies						
RF frequency	Pin 2	RF_i			2000	MHz
LO_{in} frequency	Pin 7	LO_i			2000	MHz
IF_{out} frequency	Pins 4 and 5	IF_o			300	MHz
Input level						
RF input (−1 dB comp.)	$RL = 50 \ \Omega$ Pin 2	Pi_{RF}		-15		dBm
3rd-order intercept point	$Pi_{LO} = -10$ dBm, $R_{IP3} = \infty$ Figure 2 Pin 2	IIP3		-4		dBm
LO input	Pin 7	P_{iLO}		-6	0	dBm
Impedances						
RF input	Pin 2	Z_{iRF}		25		Ω
LO input	Pin 7	Zi_{LO}		50		Ω
IF output	Pins 4 and 5	Z_{oIF}		> 10 kΩ// 0.9 pF		
Noise figure (DSB)	$Pi_{LO} = 0$ dBm, $RL > 3$ kΩ $f_{LO} = 900$ MHz	NF_{50}		9		dB
Figure 7	$f_{LO} = 1700$ MHz			12		
Voltage standing wave ratio LO	Pin 7	VSWR-LO		1.3	2	

Note: I_M = Internal mixer current (see figure 3)

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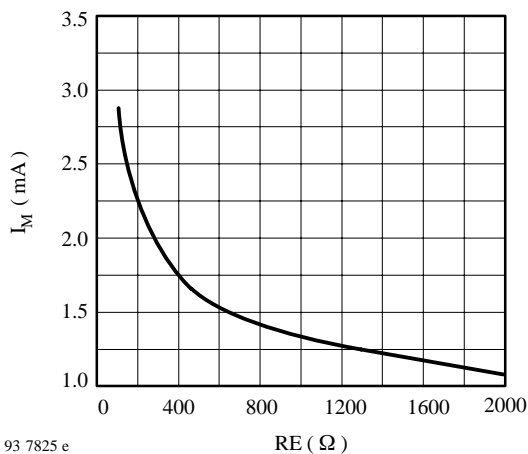
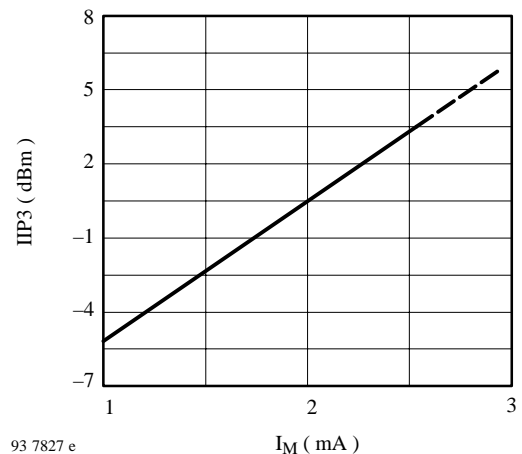Figure 3. Mixer current (I_M) versus RE

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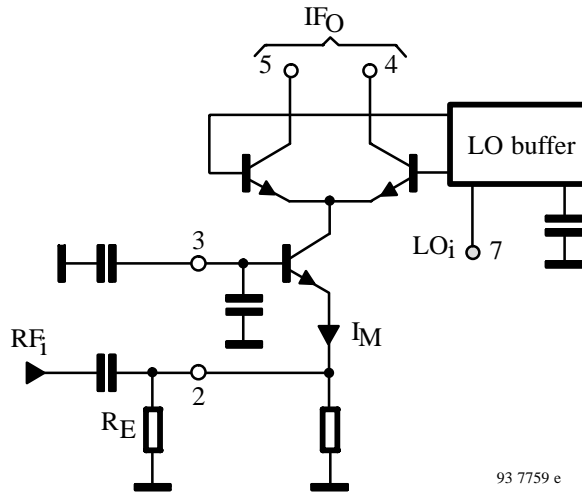Figure 4. Third-order input intercept IIP3 point versus I_M
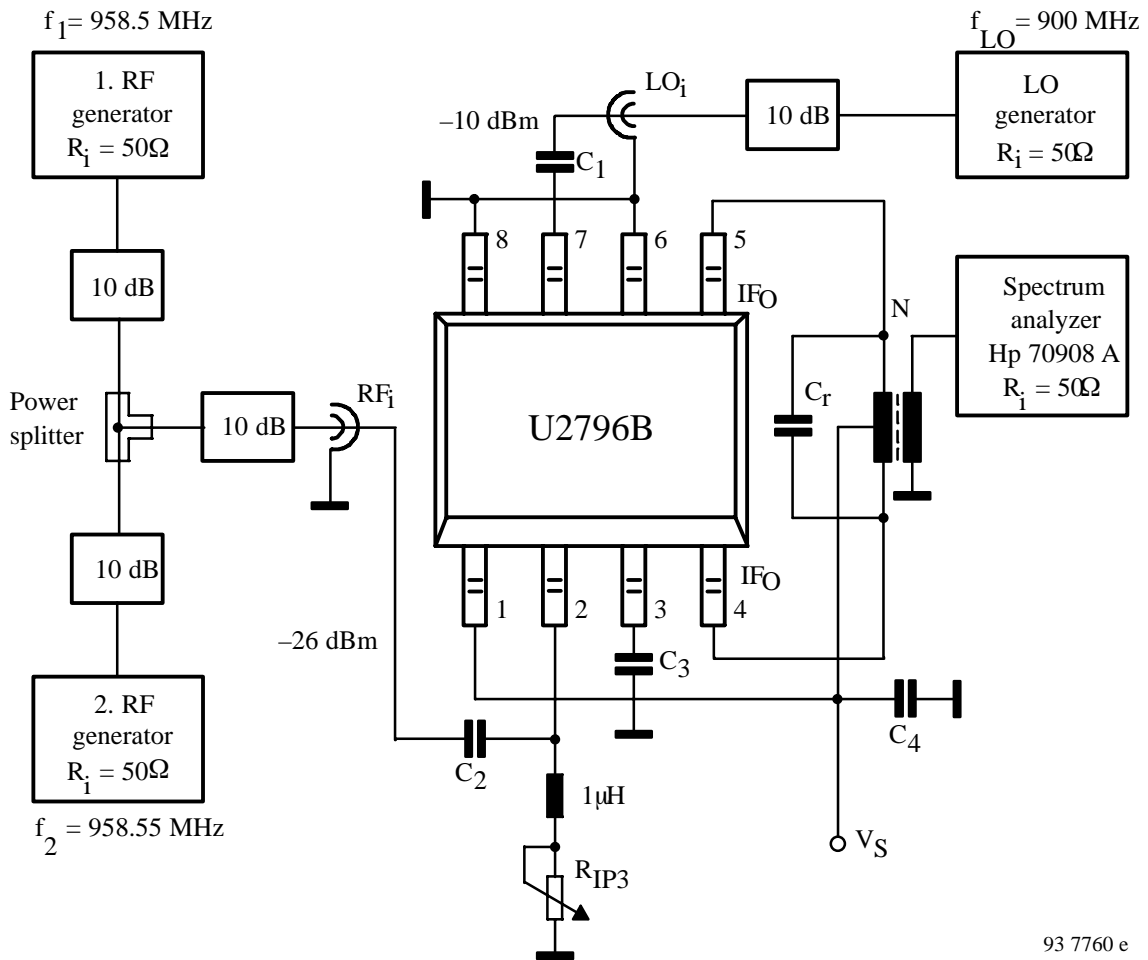
Figure 5. Mixer circuitry

Figure 6. Test circuit conversion power gain (PG$_C$) and 3rd-order input intercept point (IIP3)
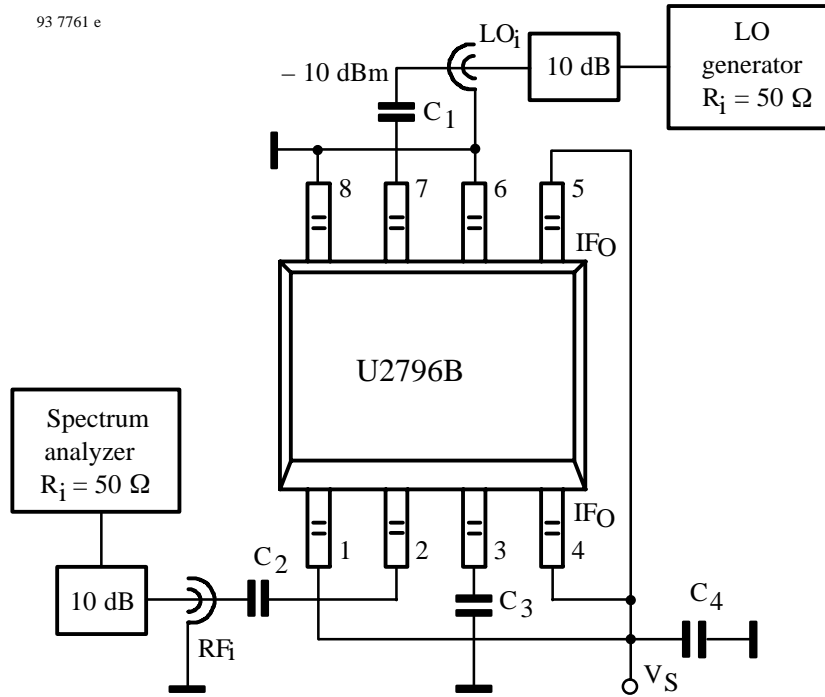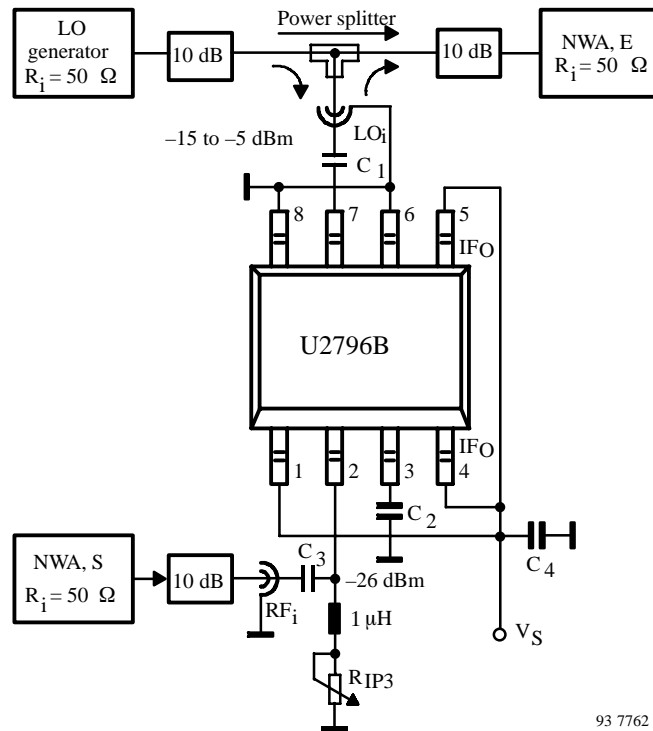
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Figure 7. Test circuit isolation LO to RF

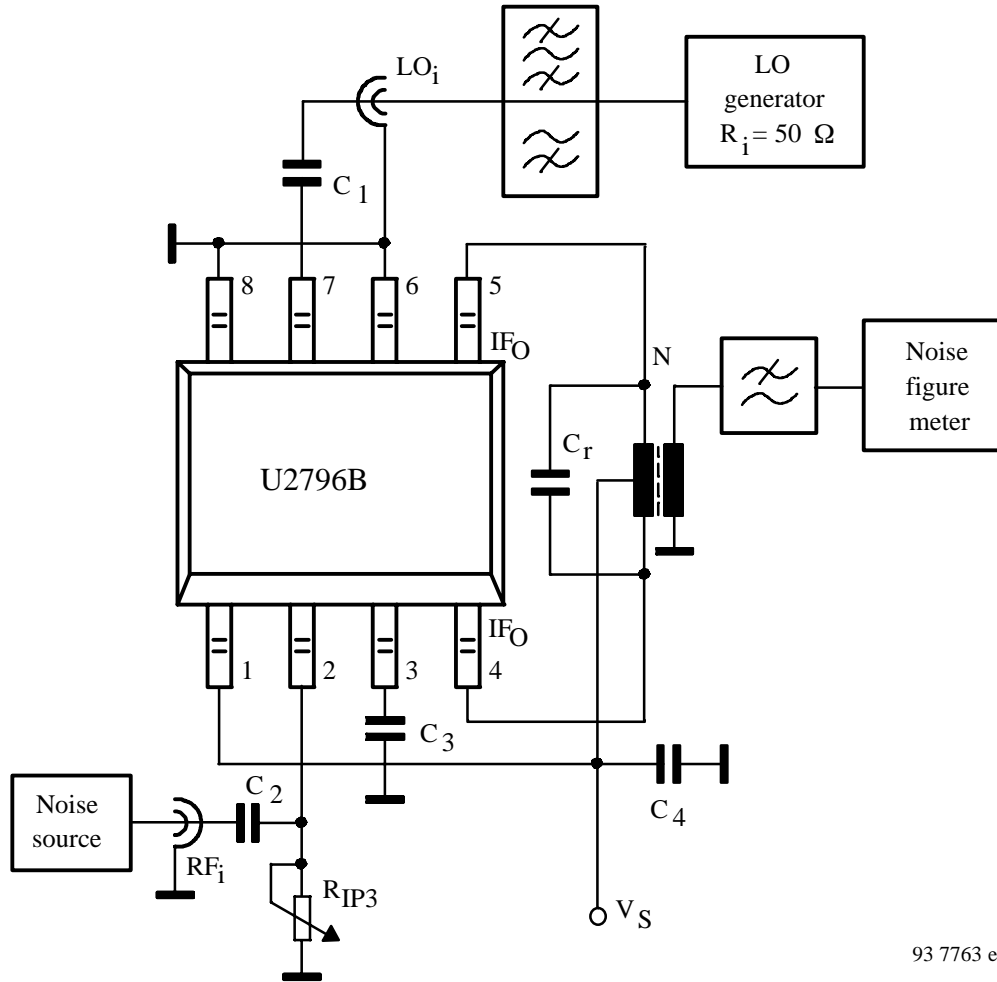Figure 8. Test circuit isolation RF to LO

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Figure 9. Test circuit noise figure

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Note:

1. The noise floor of the LO generator might influence the noise figure test result. In order to avoid this, either a bandpass or a highpass filter with fc $>$ f_{IF} should be implemented.

2. If IF output network does not provide sufficient suppression of the LO component, a lowpass filter should be inserted to avoid overdriving the noise figure meter.

3. For best noise performance 0 dBm LO power level is required.

1:   28.304 Ω   6.9746 Ω   1.11   nH
1 000.000 000 MHz
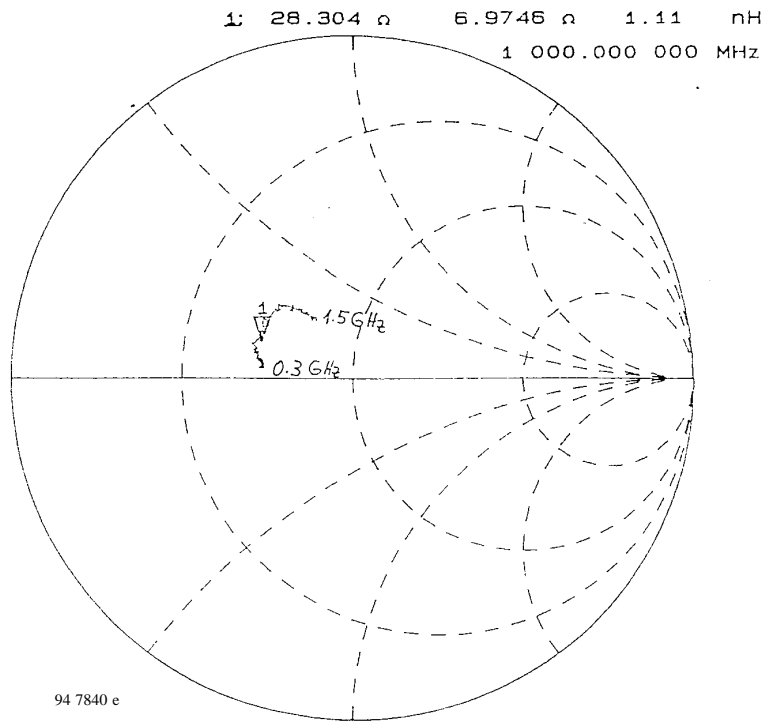
Figure 10. S11 RF input impedance

1:   42.49   Ω   −20.111 Ω   7.9137 pF
1 000.000 000 MHz
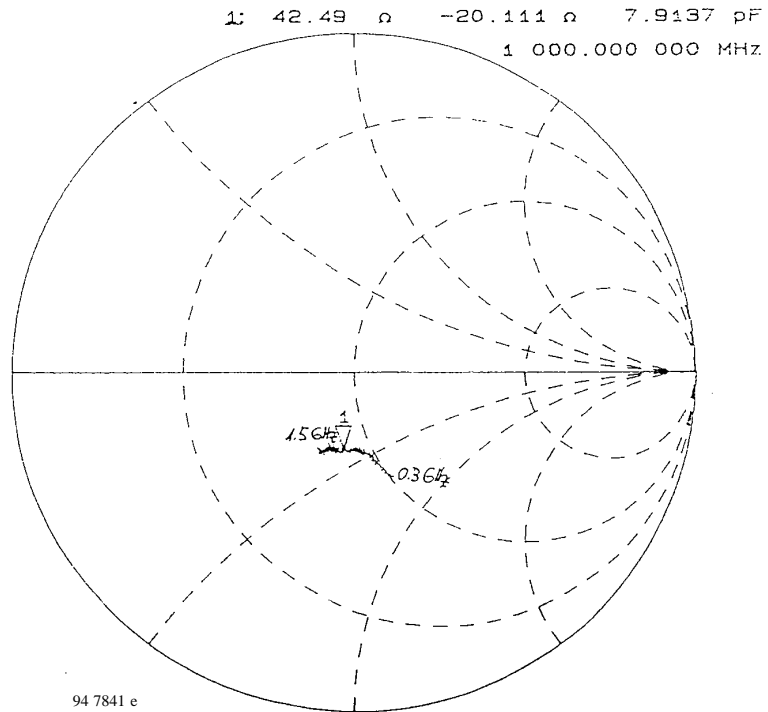
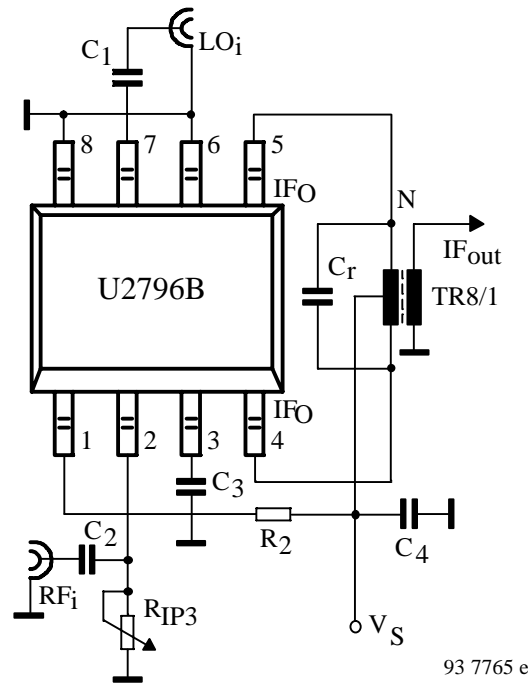Figure 11. S11 LO input impedance

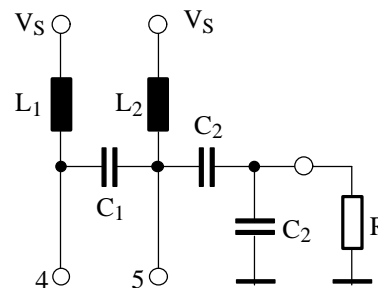## Application Circuit

Figure 12. Application circuit

Recommended Values for the Evaluator

C_1 and $C_2 = 150$ pF, C_3 and $C_4 = 100$ nF. C_r is calculated for resonance with the balun at f_{IF}, or as a highpass filter for f_{LO}. The output balun transformer ratio $> = 8:1$ for $Z_O = 50\ \Omega$. R_2 increases the IF output level and is calculated from:

$$R_2 = \frac{V_S\,(4, Minimal Minimal 5) - V_S\,(1)}{I_S\,(1)}$$

For example , $V_S\,(4, 5) = 4$ V, $V_S\,(1) = 3$ V, $I_S\,(1) = 2.2$ mA $R_2 \approx 470\ \Omega$, where $I_S\,(1)$ is the current consumption without the mixer stage.

Application Hint

The output transformer at the Pins 4 and 5 can be replaced by LC circuits as shown in figure 13. Compared to transformer, LC circuits save space and are suitable for higher IF frequencies. When applying one of these solutions, it has to be checked whether the requirements on noise figure and gain can be achieved.

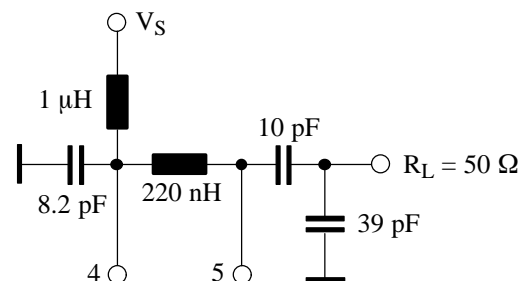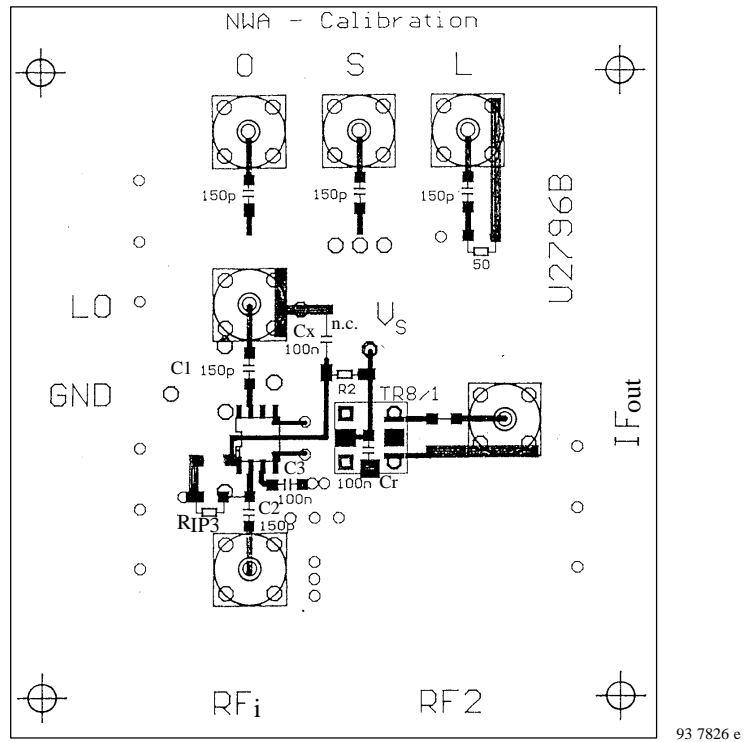The second circuit was dimensioned for approximately 130 MHz and a load resistance of 50 Ω. If, for instance, the impedance of a subsequent filter is 1 kΩ, the capacitive voltage divider may be left out.

Figure 13.

Evaluation Board

Figure 14. Evaluation board with application circuit

Package Information

Package SO8
Dimensions in mm

technical drawings
according to DIN
specifications

13034
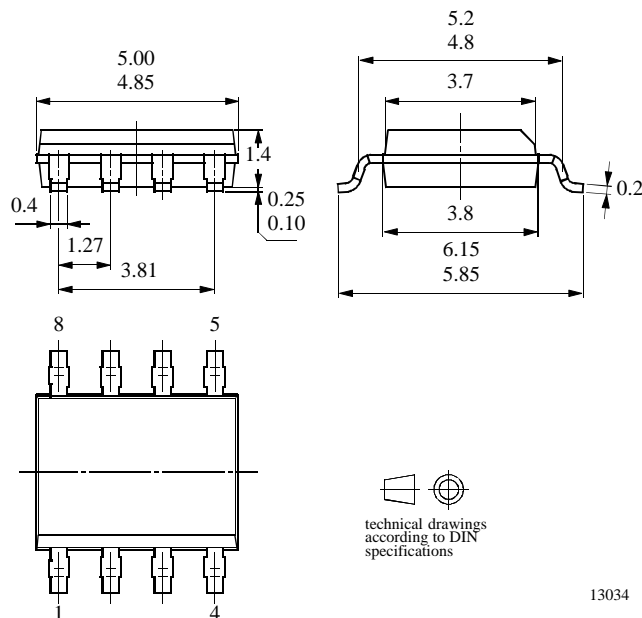
Ozone Depleting Substances Policy Statement

It is the policy of **Atmel Germany GmbH** to

1. Meet all present and future national and international statutory requirements.

2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

Atmel Germany GmbH has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively

2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA

3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

Atmel Germany GmbH can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.